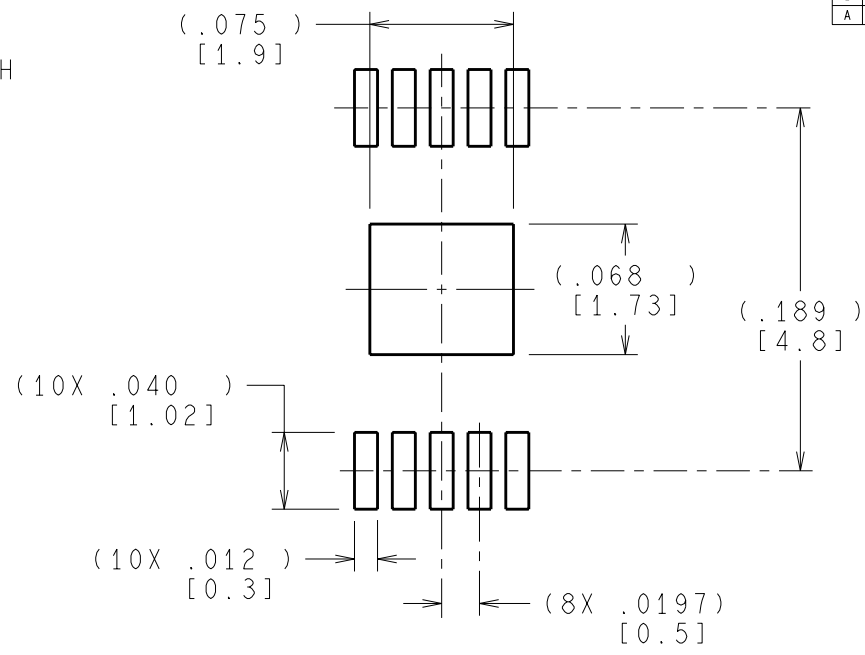
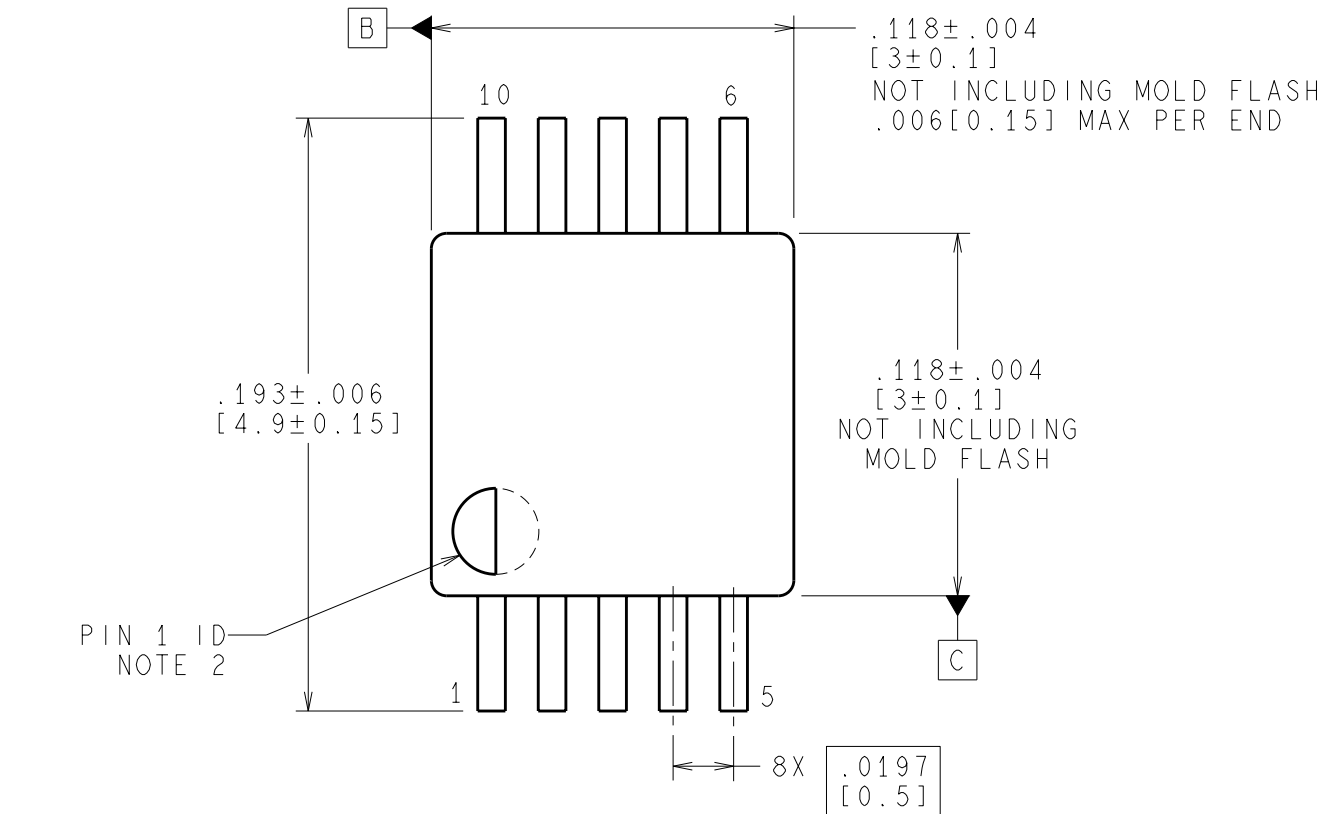
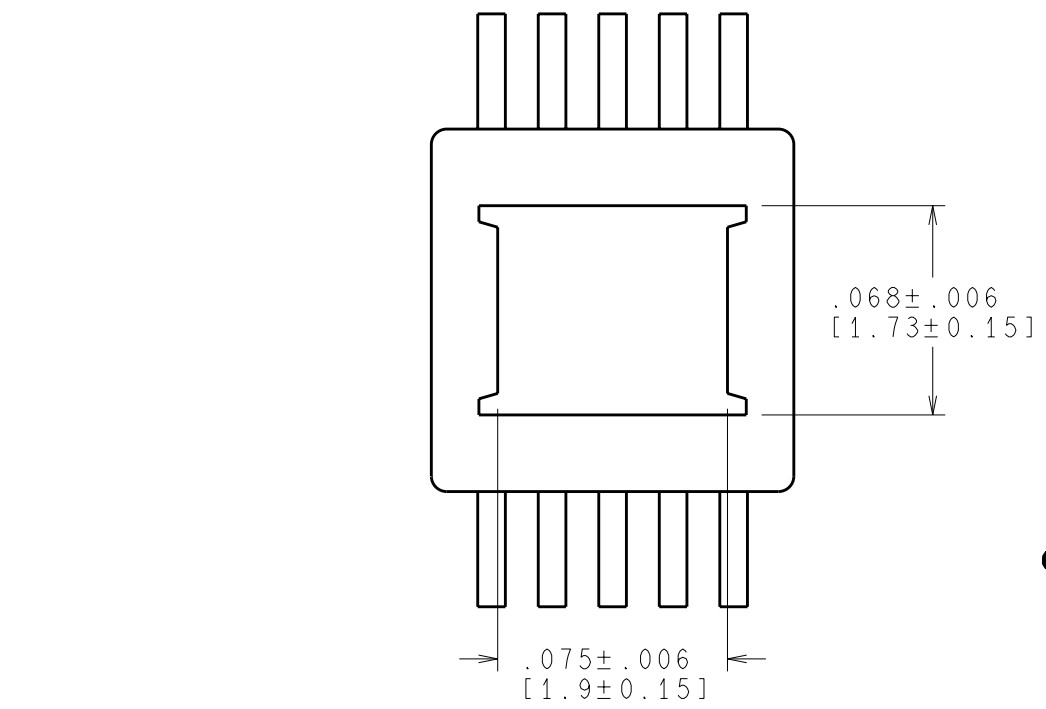
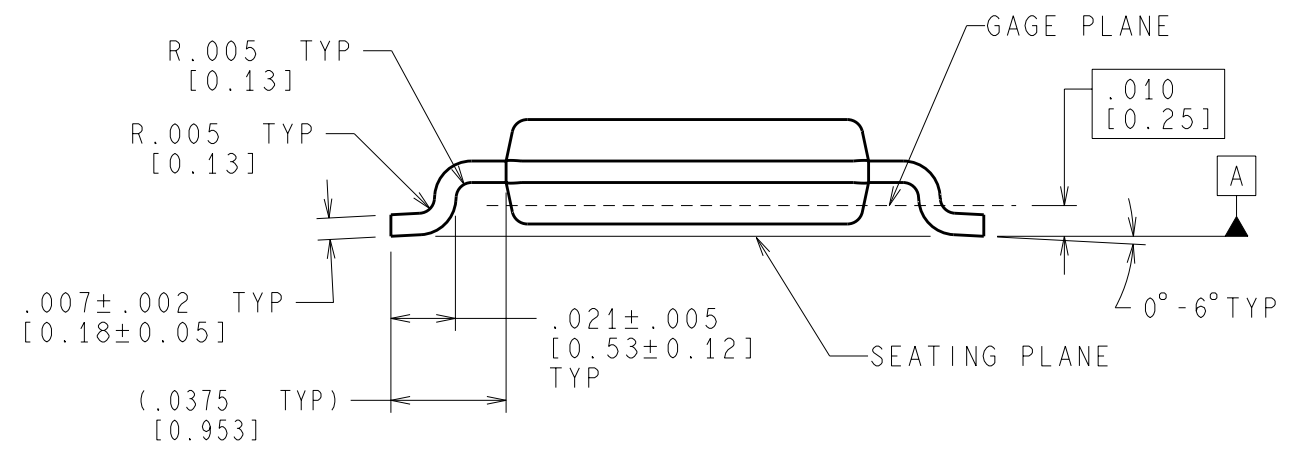
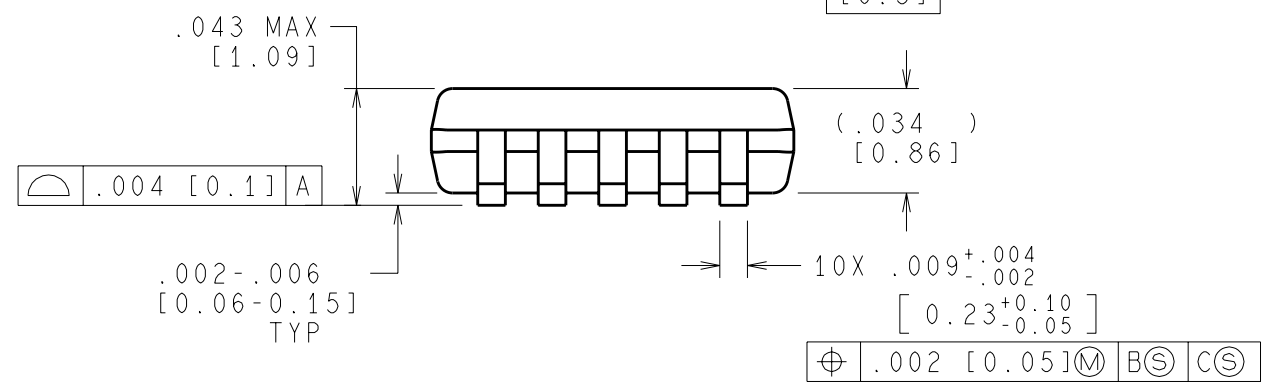


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	2078	05/22/2006	TKY/TL/PSL



RECOMMENDED LAND PATTERN



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- PIN 1 IDENTIFICATION TO HAVE HALF OR FULL CIRCLE OPTION.
- REFERENCE JEDEC REGISTRATION MO-187, VARIATION BA-T.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN	TK YH & TL	05/22/2006			
DFTG. CHK.	THANH LEQUANG	05/22/2006			
ENGR. CHK.	PS LIM	05/22/2006	MOLDDED MINI-SO, EXP PAD .118x.118x.034in, 10 LEAD, .0197in PITCH		
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		NTS	B	(SC)MKT-MUC10A	A
FORMERLY: N/A		SHEET 1 of 1			